

PATENT Attorney Docket No. 400113/ASAHINA

Art Unit: 1762

Examiner: M. Cleveland

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

HIROAKI SATOH

Application No. 09/271,447

Filed: March 18, 1999

For: PROC

PROCESS FOR FORMING A
PATTERN OF FLUORESCENT
SUBSTRATE AND PLASMA

DISPLAY PANEL

PENDING CLAIMS AFTER AMENDMENTS MADE IN RESPONSE TO OFFICE ACTION DATED JULY 12, 2001

- 1. A process for forming a pattern of fluorescent substance into the cell of a fluorescent substance display substrate, wherein a resin composition (A) layer, comprising an acrylic polymer (a) having a weight average molecular weight of 10000 to 300000 and an acid number of 80 to 250 mgKOH/g and a fluorescent substance (b), and a photosensitive resin composition (B) layer are formed inside the cell, and then they are exposed, developed and baked.
- 2. The process for forming a pattern of fluorescent substance of Claim 1, wherein a glass transition temperature Tg of the acrylic polymer (a) is below 30°C.
- 3. The process for forming a pattern of fluorescent substance of Claim 1, wherein the glass transition temperature Tg of the acrylic polymer (a) is not less than 30°C and the resin composition (A) contains an organic compound (c) having viscosity of 5-15000 mPa · sec at 20°C.

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- 4. The process for forming a pattern of fluorescent substance of Claim 3, wherein the resin composition (A) contains an organic compound (c) having viscosity of 5-15000 mPa · sec at 20°C and a polymerization inhibitor (d).
- 5. The process for forming a pattern of fluorescent substance of Claim 3, wherein the organic compound (c) is a polyhydric alcohol compound.
- 6. The process for forming a pattern of fluorescent substance of Claim 3, wherein the organic compound (c) is a compound containing at least one ethylenically unsaturated group, and the resin composition (A) contains a polymerization inhibitor (d).
- 7. The process for forming a pattern of fluorescent substance of Claim 1, wherein the resin composition (A) contains a photo polymerization initiator and/or a photo polymerization initiator assistant (e).
- 8. A process for forming a pattern of fluorescent substance into the cell of a fluorescent substance display substrate, wherein a resin composition (A) layer, comprising an acrylic polymer (a) having a weight average molecular weight of 10000 to 300000 and an acid number of 80 to 250 mgKOH/g and a fluorescent substance (b), and a photosensitive resin composition (B) layer are formed inside the cell, and then they are exposed, developed and baked, wherein the photosensitive resin composition (B) layer is formed in the cell after the resin composition (A) layer is formed.
- 10. The process for forming a pattern of fluorescent substance of Claim 8, wherein a glass transition temperature Tg of the acrylic polymer (a) is below 30°C.
- 11. The process for forming a pattern of fluorescent substance of Claim 8, wherein the glass transition temperature Tg of the acrylic polymer (a) is not less than 30°C and the resin composition (A) contains an organic compound (c) having viscosity of 5-15000 mPa · sec at 20°C.

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- 12. The process for forming a pattern of fluorescent substance of Claim 11, wherein the resin composition (A) contains an organic compound (c) having viscosity of 5-15000 mPa · sec at 20°C and a polymerization inhibitor (d).
- 13. The process for forming a pattern of fluorescent substance of Claim 11, wherein the organic compound (c) is a polyhydric alcohol compound.
- 14. The process for forming a pattern of fluorescent substance of Claim 11, wherein the organic compound (c) is a compound containing at least one ethylenically unsaturated group, and the resin composition (A) contains a polymerization inhibitor (d).
- 15. The process for forming a pattern of fluorescent substance of Claim 8, wherein the resin composition (A) contains a photo polymerization initiator and/or a photo polymerization initiator assistant (e).

Amendment or ROA - Regular (Rev. 6/11/2001)